What is claimed is:

1. A~~n~~ method of manufacture of an integrated circuit package system comprising:

providing a substrate;

coupling an integrated circuit to the substrate;

mounting a shielding element having segments around the integrated circuit;

linking a tie bar to a segment and another segment of the segments of the shielding element;

applying a conductive shielding layer on the shielding element; and

coupling a system interconnect to the shielding element.

2. The ~~system~~method as claimed in claim 1 further comprising applying a conductive adhesive between the shielding element and the substrate.

3. The ~~system~~method as claimed in claim 1 wherein coupling the system interconnect includes:

electrically connecting a pad to the shielding element;

coupling a via to the pad; and

attaching the system interconnect to the pad.

4. The ~~system~~method as claimed in claim 1 further comprising molding an insulating compound on the substrate, the integrated circuit, and the shielding element including leaving a contact exposed.

5. The ~~system~~method as claimed in claim 1 further comprising forming a shield element segment, having an opening, including linking a tie bar between the shield element segments for forming the shielding element.

6. A~~n~~ method of manufacture of an integrated circuit package system comprising:

providing a substrate including providing a strip substrate or a system in package substrate;

coupling an integrated circuit to the substrate including coupling a wire bond integrated circuit, a flip chip integrated circuit, or a combination thereof;

mounting a shielding element having segments around the integrated circuit including adhering the shielding element to the substrate;

linking a tie bar to a segment and another segment of the shielding element;

applying a conductive shielding layer on the shielding element including applying the conductive shielding layer over the integrated circuit; and

coupling a system interconnect to the shielding element including coupling the conductive shielding layer.

7. The ~~system~~method as claimed in claim 6 further comprising applying a conductive adhesive between the shielding element and the substrate including electrically connecting a pad in the substrate to the shielding element.

8. The ~~system~~method as claimed in claim 6 wherein coupling the system interconnect includes:

electrically connecting a pad to the shielding element;

coupling a via to the pad including accessing the pad on a component side and a system side of the substrate;

forming the system interconnect on the via including forming solder paste, a solder ball, a solder bump, a solder column, or a stud bump; and

attaching the system interconnect including linking the via, the pad, the shielding element, and conductive shielding layer.

9. The ~~system~~method as claimed in claim 6 further comprising molding an insulating compound on the substrate, the integrated circuit, and the shielding element including leaving a contact exposed including forming a groove, having a lateral side, for exposing the contact.

10. The ~~system~~method as claimed in claim 6 further comprising forming a shield element segment, having an opening, including linking ~~a~~the tie bar between the shield element segments for forming the shielding element in which having the opening may include forming a rectangular opening, a short rectangular opening, or a round opening.

11. An integrated circuit package system comprising:

a substrate;

an integrated circuit coupled to the substrate;

a shielding element having segments around the integrated circuit;

a tie bar linking a segment and another segment of the shielding element;

a conductive shielding layer on the shielding element; and

a system interconnect coupled to the shielding element.

12. The system as claimed in claim 11 further comprising a conductive adhesive between the shielding element and the substrate.

13. The system as claimed in claim 11 wherein the system interconnect coupled includes:

a pad electrically connected to the shielding element;

a via coupled to the pad; and

the system interconnect attached to the pad.

14. The system as claimed in claim 11 further comprising an insulating compound molded on the substrate, the integrated circuit, and the shielding element with a contact exposed.

15. The system as claimed in claim 11 further comprising a shield element segment, having an opening, with a tie bar between the shield element segments for forming the shielding element.

16. The system as claimed in claim 11 further comprising:

a strip substrate or a system in package substrate;

a wire bond integrated circuit, a flip chip integrated circuit, or a combination thereof coupled to the substrate; and

wherein:

the conductive shielding layer applied over the integrated circuit; and

the conductive shielding layer and the shielding element coupled to the system interconnect.

17. The system as claimed in claim 16 further comprising a conductive adhesive between the shielding element and the substrate includes a pad in the substrate electrically connected to the shielding element.

18. The system as claimed in claim 16 wherein the system interconnect coupled includes:

a pad electrically connected to the shielding element;

a via coupled to the pad including the pad accessed on a component side, a system side of the substrate, or both; and

the system interconnect on the via includes solder paste, a solder ball, a solder bump, a solder column, or a stud bump attached to the via.

19. The system as claimed in claim 16 further comprising an insulating compound molded on the substrate, the integrated circuit, and the shielding element includes a contact left exposed including a lateral side, for exposing the contact.

20. The system as claimed in claim 16 further comprising a shield element segment with an opening, includes ~~a~~the tie bar between the shield element segments for

forming the shielding element in which the opening may include a rectangular opening, a short rectangular opening, or a round opening.